

# CHEMTRONICS® Technical Data Sheet

**TDS # SWNoClean**

## Soder-Wick® No Clean Desoldering Braid

### PRODUCT DESCRIPTION

Soder-Wick® No Clean is designed to provide fast and safe desoldering without leaving behind harmful flux residues. Soder-Wick® No Clean uses pure, oxygen free copper braid and a patented flux technology to make an efficient and effective desoldering braid. Soder-Wick® No Clean SD is available on ESD safe bobbins for protection against damage due to static electricity.


- Requires little or no post solder cleaning
- No corrosive residues
- Halide free
- ESD Safe bobbins meet specs:  
MIL-STD-1686C  
MIL-HDBK-263B  
Static decay provision of  
MIL-B-81705C
- Minimal risk of heat and static component damage

### TYPICAL APPLICATIONS

Soder-Wick® No Clean safely removes solder from:

- Lugs and Posts
- Micro Circuits
- Surface Mount Device Pads
- Ball Grid Array Pads

### TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Surface Insulation Resistance			
<b>Bellcore TR-NWT-000078 : PASS</b> After 96 Hours (megohms) $2 \times 10^4$ Limit			
<u>Group A</u> $4.8 \times 10^6$	<u>Group B</u> $3.8 \times 10^6$	<u>Group C</u> $4.1 \times 10^6$	
<b>ANSI/IPC J SF-818 : PASS</b> After 168 Hours (ohms) $1.8 \times 10^8$ Limit			
<u>1-2</u> $2.3 \times 10^{10}$	<u>2-3</u> $2.6 \times 10^{10}$	<u>3-4</u> $2.8 \times 10^{10}$	<u>4-5</u> $2.8 \times 10^{10}$
<b>Electromigration : PASS</b> Average Insulation Resistance (megohms)-One Decade Limit			
	<u>Initial</u>	<u>Final</u>	
Group E	$3.93 \times 10^3$	$1.24 \times 10^4$	
Group F	$3.87 \times 10^3$	$2.84 \times 10^4$	
At 10x magnification no evidence of electromigration or heavy corrosion.			
<b>Silver Chromate Test Paper</b>		<b>PASS</b>	
<b>Copper Mirror Test</b>		<b>PASS</b>	
<b>Shelflife</b>		<b>2 years</b>	
<b>RoHS/WEEE Status</b>			

### SODER-WICK® NO CLEAN MEETS OR EXCEEDS:

MIL-F-14256F, Type R  
DOD-STD-883E, Method 2022  
Bellcore TR-NWT-000078  
ANSI/IPC J SF-818

Part #	Size Inches	Color	Size Metric
1	.030"	White	.76mm
2	.060"	Yellow	1.52mm
3	.080"	Green	2.03mm
4	.110"	Blue	2.79mm
5	.145"	Brown	3.68mm
6	.210"	Red	5.33mm
BGA	-	Purple	-

## AVAILABILITY

Part #	Size	Length	Part #	Size	Length
60-1-5	1	5	60-1-10	1	10
60-2-5	2	5	60-2-10	2	10
60-3-5	3	5	60-3-10	3	10
60-4-5	4	5	60-4-10	4	10
60-5-5	5	5	60-5-10	5	10
60-6-5	6	5			

## USAGE INSTRUCTIONS

For industrial use only.

Read MSDS carefully prior to use.

- 1) Choose a Soder-Wick® No Clean width equal to or slightly larger than the pad or connection.
- 2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
- 3) Set temperature of iron between 600-750°F.
- 4) Place wick on solder joint and place tip of hot iron on top of wick.
- 5) As solder becomes molten, the color of the wick will change from copper to silver.
- 6) Remove wick and iron from joint simultaneously once color change has stopped.
- 7) The component lead / pad is now clean and free from solder.
- 8) Clip and discard used portion of the wick.

## TECHNICAL & APPLICATION ASSISTANCE

Chemtronics® provides a technical hotline to answer your technical and application related questions. The toll free number is: **1-800-TECH-401.**

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<b>VacuPak™ Packaging</b>	Part #	Size
The VacuPak™ Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.	SW16015	1
	SW16025	2
	SW16035	3
	SW16045	4
	SW16055	5
	SW160BGA	BGA

## NOTE:

This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. ITW Chemtronics® does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

## MANUFACTURED BY:

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